

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
SHINYA SASAGAWA	06/22/2016
MOTOMU KURATA	06/23/2016
SATORU OKAMOTO	06/22/2016
SHUNPEI YAMAZAKI	06/22/2016
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SEMICONDUCTOR ENERGY LABORATORY CO., LTD.
<b>Street Address:</b>	398, HASE
<b>City:</b>	ATSUGI-SHI, KANAGAWA-KEN
<b>State/Country:</b>	JAPAN
<b>Postal Code:</b>	243-0036
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	15193564
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<b>ATTORNEY DOCKET NUMBER:</b>	12732-1708001
<b>NAME OF SUBMITTER:</b>	JANELLE A. JACKSON
<b>SIGNATURE:</b>	/Janelle A. Jackson/
<b>DATE SIGNED:</b>	06/29/2016
<b>Total Attachments: 2</b>	
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source=12732-1708001 Assignment#page2.tif	

## ASSIGNMENT

For valuable consideration, We, Shinya SASAGAWA of Chigasaki, Kanagawa, Japan, Motomu KURATA of Isehara, Kanagawa, Japan, Satoru OKAMOTO of Isehara, Kanagawa, Japan and Shunpei YAMAZAKI of Setagaya, Tokyo, Japan hereby assign to Semiconductor Energy Laboratory Co., Ltd., a Japanese corporation having a place of business at:


398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by us this day, entitled SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF, filed June 27, 2016, and assigned U.S. Serial Number 15/193,564, and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Signature Shinya Sasagawa  
Name: Shinya SASAGAWA  
Date: 06/22/2016

Signature Motomu Kurata  
Name: Motomu KURATA  
Date: 06/23/2016

Signature Satoru Okamoto  
Name: Satoru OKAMOTO  
Date: 06/22/2016

Signature   
Name: Shunpei YAMAZAKI  
Date: 06/22/2016